



S1141

(UL ANSI:FR-4)UV Blocking

特点

- Tg140℃ (DSC)。
- UV Blocking/AOI兼容。
- 优良的机械加工性能。

FEATURES

- Tg140℃ (DSC).
- UV Blocking/AOI Compatible.
- Excellent mechanical processability.

应用领域

电脑、仪器仪表、摄像机、通讯设备、
电子游戏机、汽车、航空等。

APPLICATIONS

Computer, Instrumentation, VCR,
communication equipment, electronic
game machine, automotive electronics,
aviation, and etc.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data	
			SPEC	Typical Value
Tg	DSC	℃	≥130	140
Flammability	C-48/23/50	Rating	V-0	V-0
	E-24/125			
Volume Resistivity	After moisture resistance	M Ω ·cm	≥10 ⁶	5.2×10 ⁸
	E-24/125		≥10 ³	5.2×10 ⁶
Surface Resistivity	After moisture resistance	M Ω	≥10 ⁴	5.4×10 ⁷
	E-24/125		≥10 ³	5.6×10 ⁶
Arc Resistance	D-48/50+D-0.5/23	S	≥60	120
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥40	60
Dielectric Constant (1MHz)	C-24/23/50	-	≤5.4	4.6
Dissipation Factor (1MHz)	C-24/23/50	-	≤0.035	0.015
Thermal Stress	Unetched	288℃, solder dip	>10s	60s
	Etched		No delamination	No delamination
Peel Strength	1oz	288℃, 10s	≥1.05	1.8
	Cu. Foil	125℃	≥0.70	1.6
Flexural Strength	LW	A	≥415	600
	CW		≥345	500
Water Absorption	D-24/23	%	≤0.80	0.15
CTE Z-axis	Before Tg	TMA	μ m/m℃	65
	After Tg	TMA	μ m/m℃	300
	50~260℃	TMA	%	4.5
Td	10℃/min, N ₂ , 5% Wt Loss	℃	-	310
T260	TMA	min	-	15
T288	TMA	min	-	2
CTI	IEC60112 Method	V	PLC 3(175V--249V)	PLC 3

Remarks: 1. Specification sheet: IPC-4101/21, is for your reference only.

2. All the typical value is based on the 1.6mm specimen, while the Tg is for specimen ≥0.50mm.

3. All the typical value listed above is for your reference only, please turn to Shengyi Sci. Tech. Co., Ltd. for detailed information, and all rights from this data sheet are reserved by Shengyi Sci. Tech. Co., Ltd.

Explanations: C = Humidity conditioning; D = Immersion conditioning in distilled water; E = Temperature conditioning.

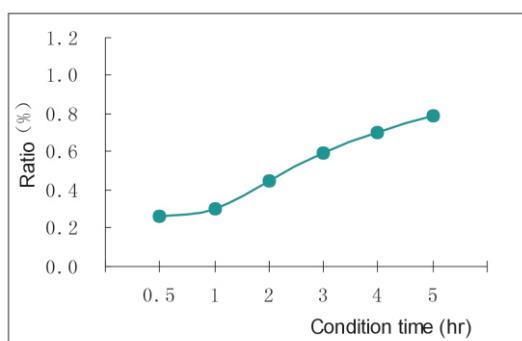
The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in ℃ and with the third digit the relative humidity.



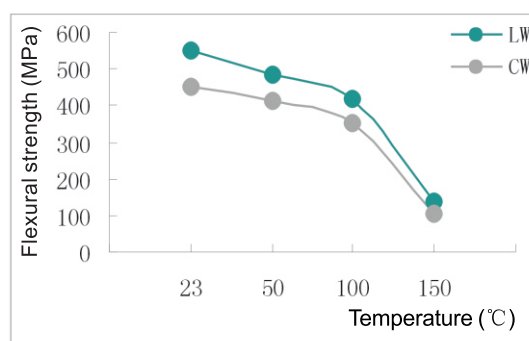
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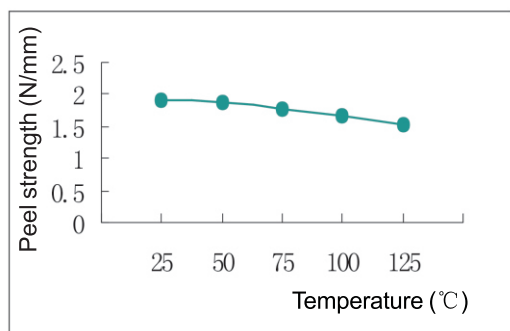
Water absorption at pressure cooker



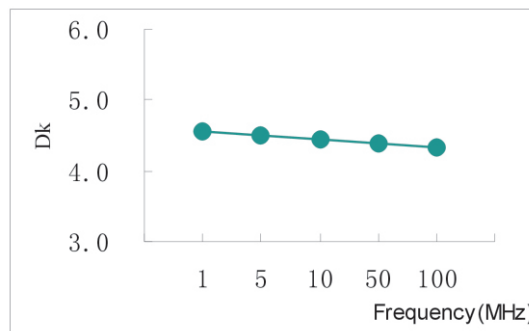
Flexural strength



Peel strength



Dielectric constant



PURCHASING INFORMATION

Thickness	Copper foil	Standard Size
0.05mm to 3.2mm	12 μ m to 105 μ m	1,020×1,220mm (40" × 48") 915×1,220mm (36" × 48") 1,070×1,220mm (42" × 48")

- ❖ Other sheet size and thickness could be available upon request.
- ❖ UL认可单、双面PCB板，最小厚度0.38mm。

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S0401 PREPREG

(UL ANSI:FR-4) Bonding Prepreg For S1141

特点

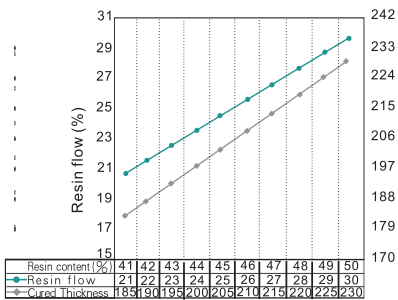
- Tg140℃ (DSC)。
- UV Blocking/AOI兼容。
- 优良的粘结性能，作业窗口宽。

FEATURES

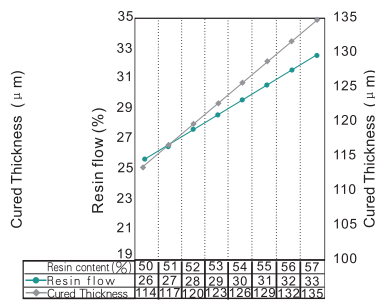
- Tg140℃ (DSC) .
- UV Blocking/AOI Compatible.
- Excellent bonding strength ,wide operating window.

PREPREG PARAMETERS

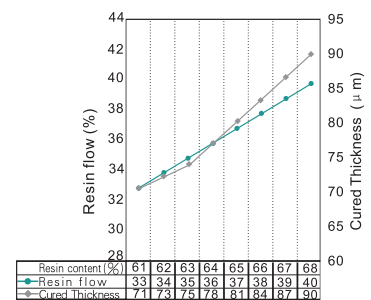
7628 TYPE PREPREG



2116 TYPE PREPREG



1080 TYPE PREPREG



Designation	Glass fabric type	Performance	Gel time (sec)	Resin Content (%)	Resin flow (%)	Cured Thickness (μm)	Standard Size (roll type)
S0401	106	UV Blocking	160±20	71±3	37±5	50±10	1,260mm×114.3m (125yards)
	106LD			71±3	37±5	50±10	
	1078LD			64±3	36±5	78±10	
	1080			X±3	X±5	X±10	
	1086LD			61±3	33±5	78±10	
	2112		150±20	57±3	30±5	90±15	
	2113			56±3	26±5	100±15	
	2313			55±3	26±5	100±15	
	3313			55±3	26±5	100±15	
	2116			X±3	X±5	X±15	
	2165			52±3	26±5	140±15	
	1500			45±3	22±5	160±15	
	7628			X±3	X±5	X±20	

Type, Resin Content and Size Could be Available Upon Request

Prepreg Test Method www.atechcircuit.com

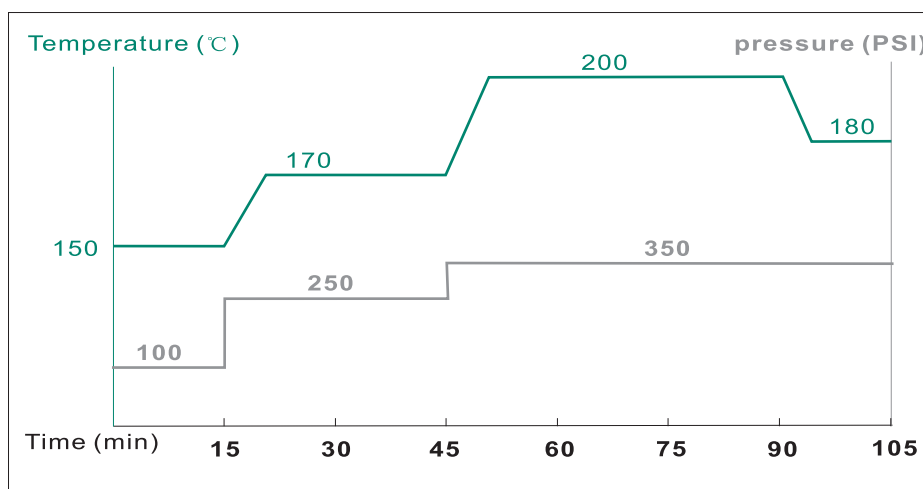
- Resin Content, Resin Flow, Gel Time: IPC-TM-650



S0401 PREPREG

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HOT PRESSING CYCLE



Heat-up rate: 1.0~2.5°C/min(80~140°C)

Curing time: >30min(170~180°C)

The hot pressing parameters is for your reference only, please turn to Shengyi Sci.Tech.Co., Ltd for detailed information.

PREPREG STORAGE

STORAGE CONDITION

- Three months when stored at <23 °C and <50% RH .
- Six months when stored at <5 °C . Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Were kept in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.

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